

## **Master Bond EP21TDCS Silver Filled Electrically Conductive Epoxy Compound**

Category: Polymer, Adhesive, Thermoset, Epoxy, Epoxy Adhesive

## **Material Notes:**

Master Bond Polymer System EP21TDCS is a two component, silver filled, electrically conductive adhesive for high performance bonding and sealing formulated to cure at room temperature or more rapidly at elevated temperatures. Unlike the majority of two part silver conductive epoxy systems, the EP21TDCS has a one-to-one mix ratio, by weight or volume.

## Order this product through the following link:

http://www.lookpolymers.com/polymer\_Master-Bond-EP21TDCS-Silver-Filled-Electrically-Conductive-Epoxy-Compound.php

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	121 °C	250 °F	
Minimum Service Temperature, Air	-269 °C	-453 °F	

Processing Properties	Metric	English	Comments
Cure Time	60.0 - 120 min	1.00 - 2.00 hour	
	@Temperature 93.3 °C	@Temperature 200 °F	
	1440 - 2160 min	24.0 - 36.0 hour	
	@Temperature 23.0 °C	@Temperature 73.4 °F	

Descriptive Properties	Value	Comments
Color Code	"A" Silver; "B" Silver	
Mix Ratio By Weight	100/100	
Set-Up Time, minutes	30-40	At Room Temperature
Viscosity	Smooth Paste	Room Temperature

## Contact Songhan Plastic Technology Co.,Ltd.

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